

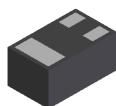
Product Summary

Part Number	R1 (NOM)	R2 (NOM)	Marking
DDTA144ELP	47kΩ	47kΩ	P2

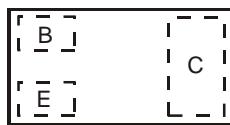
Features

- Epitaxial Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- Totally Lead Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

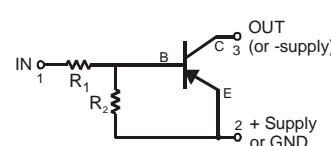
X1-DFN1006-3



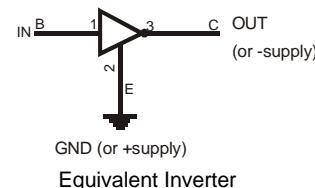
Bottom View



Top View
Pin-Out



Device Symbol



Equivalent Inverter
Circuit

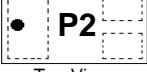
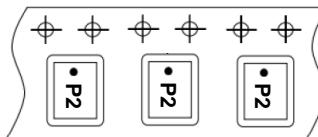
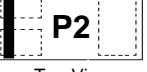
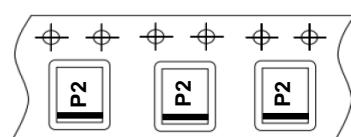
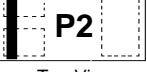
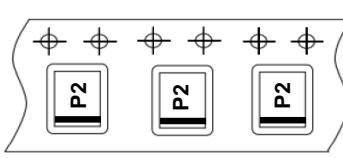
Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTA144ELP-7	P2	7	8	3,000
DDTA144ELP-7B	P2	7	8	10,000

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information

DDTA144ELP-7	 <p>Top View Dot Denotes Collector Side</p> 	<p>From date code 1527 (YYWW), this changes to:</p>  <p>Top View Bar Denotes Base and Emitter Side</p> 
	 <p>Top View Bar Denotes Base and Emitter Side</p> 	<p>P2 = Product Type Marking Code</p>

Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage	V_{CC}	-50	V
Input Voltage	V_{IN}	+10 to -40	V
Output Current (I_O)	$I_C(\text{MAX})$	-200	mA

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	250	mW
Power Deration above $+25^\circ\text{C}$	P_{der}	2	mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient Air (Note 5) (Equivalent to one heated junction of PNP)	$R_{\theta JA}$	500	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Off Characteristics (Notes 6 & 7)						
Collector-Base Breakdown Voltage	BV_{CBO}	-50	—	—	V	$I_C = -10\mu\text{A}, I_E = 0$
Collector-Emitter Breakdown Voltage	BV_{CEO}	-50	—	—	V	$I_C = -1\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	-4.5	—	—	V	$I_E = -100\mu\text{A}, I_C = 0$
Collector Cutoff Current	I_{CEX}	—	—	-100	nA	$V_{CE} = -50\text{V}, V_{EB(\text{OFF})} = 3\text{V}$
Base Cutoff Current (I_{BEX})	I_{BL}	—	—	-60	μA	$V_{CE} = -50\text{V}, V_{EB(\text{OFF})} = 3\text{V}$
Collector-Base Cut Off Current	I_{CBO}	—	—	-100	nA	$V_{CB} = -50\text{V}, I_E = 0$
Collector-Emitter Cut Off Current, $I_{O(\text{off})}$	I_{CES}	—	—	-100	nA	$V_{CE} = -50\text{V}, I_B = 0$
Emitter-Base Cut Off Current	I_{EBO}	—	—	-100	μA	$V_{EB} = -4\text{V}, I_C = 0$
Input Off Voltage	$V_{I(\text{off})}$	-300	—	—	mV	$V_{CC} = -5\text{V}, I_O = -100\mu\text{A}$
On Characteristics (Notes 6 & 7)						
Input-On Voltage	$V_{I(\text{on})}$	—	—	-3	V	$V_O = -0.3\text{V}, I_O = -5\text{mA}$
Input Current	I_I	—	—	-180	μA	$V_I = -5\text{V}$
DC Current Gain	h_{FE}	90	—	—	—	$V_{CE} = -5\text{V}, I_C = -2.5\text{mA}$
		120	—	—	—	$V_{CE} = -5\text{V}, I_C = -5\text{mA}$
		150	—	—	—	$V_{CE} = -5\text{V}, I_C = -10\text{mA}$
		100	—	—	—	$V_{CE} = -5\text{V}, I_C = -100\text{mA}$
		180	—	—	—	$V_{CE} = -5\text{V}, I_C = -200\text{mA}$
		250	—	—	—	$V_{CE} = -5\text{V}, I_C = -300\text{mA}$
Output On Voltage (Collector-Emitter Saturation Voltage)	$V_{O(\text{on})}$	—	—	-150	mV	$I_I = -1\text{mA}, I_O = -10\text{mA}$
		—	—	-800	mV	$I_I = -1\text{mA}, I_O = -40\text{mA}$
Input Resistance	R_1	33	47	61	k Ω	—
Resistance Ratio	(R_2/R_1)	0.8	1	1.2	—	—
Small Signal Characteristics						
Current Gain-Bandwidth Product	f_T	—	250	—	MHz	$V_{CE} = -10\text{V}, I_E = -5\text{mA}, f = 100\text{ MHz}$

Notes:

5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
6. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.
7. Guaranteed by design.

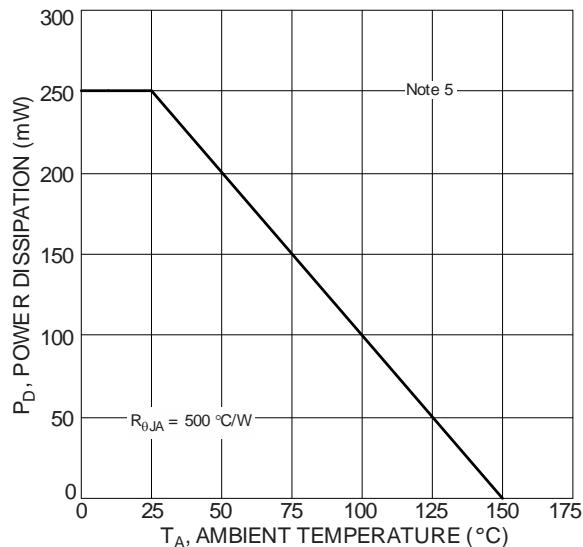


Fig. 1 Power Dissipation vs. Ambient Temperature

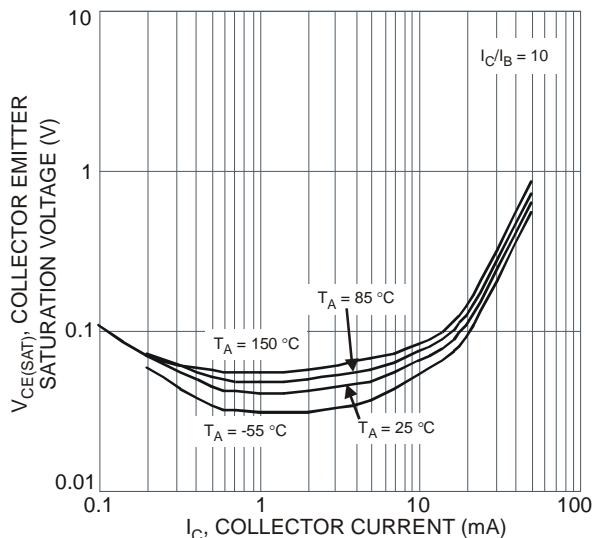


Fig. 3 Typical Collector Emitter Saturation Voltage vs. Collector Current

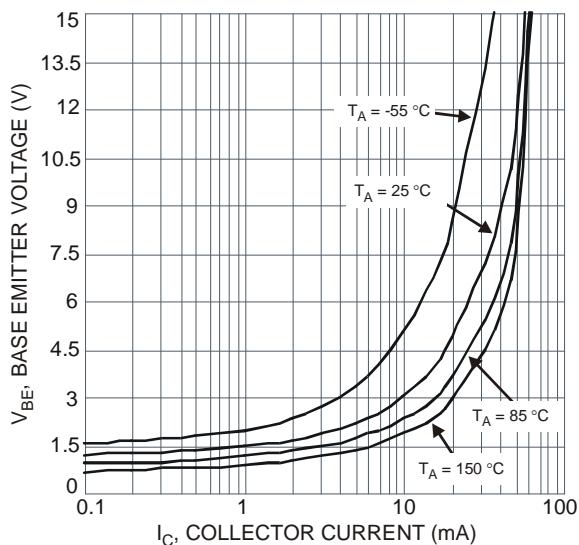


Fig. 5 Typical Base Emitter Voltage vs. Collector Current

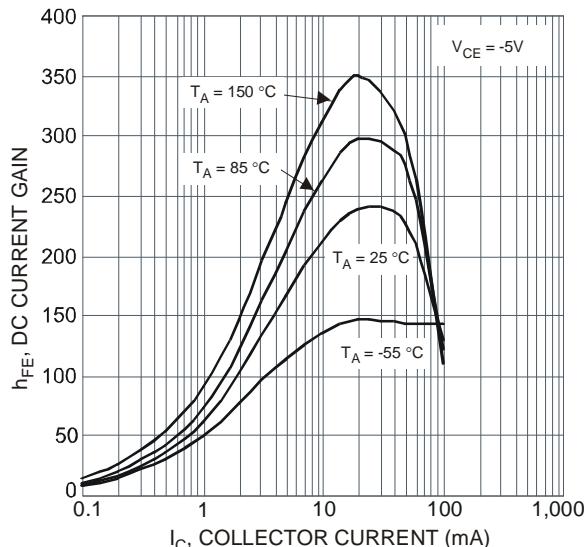


Fig. 2 Typical DC Current Gain vs. Collector Current

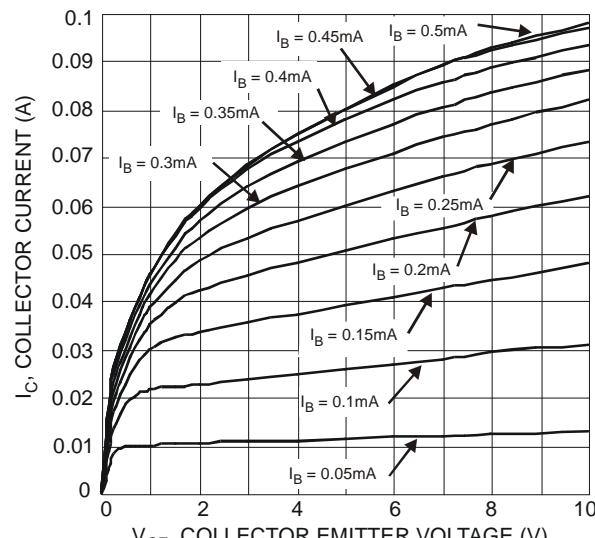


Fig. 4 Typical Collector Emitter Voltage vs. Collector Current

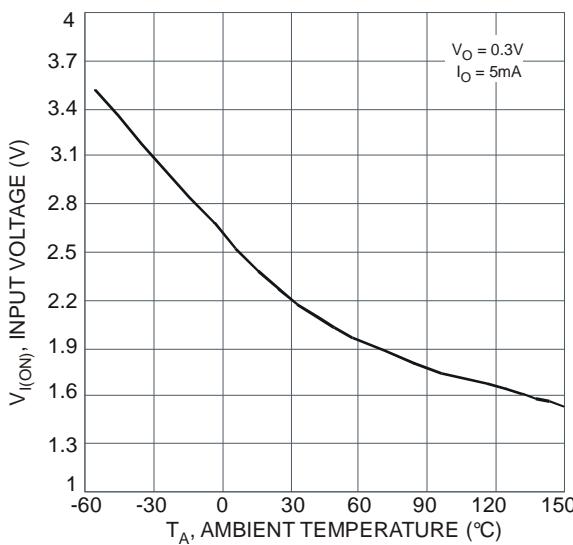


Fig. 6 Typical Input Voltage vs. Ambient Temperature

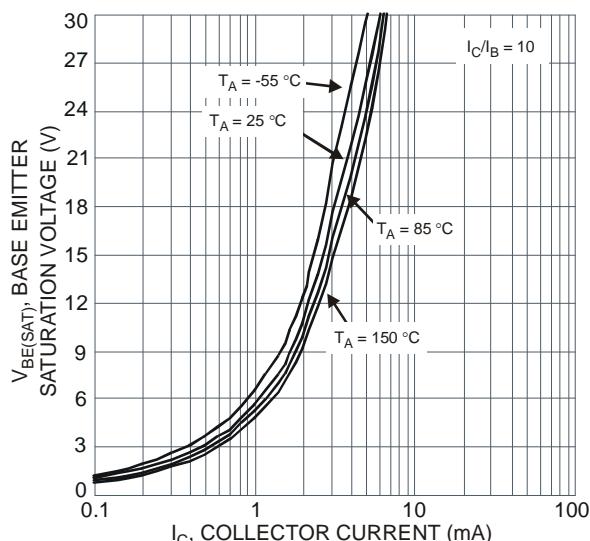
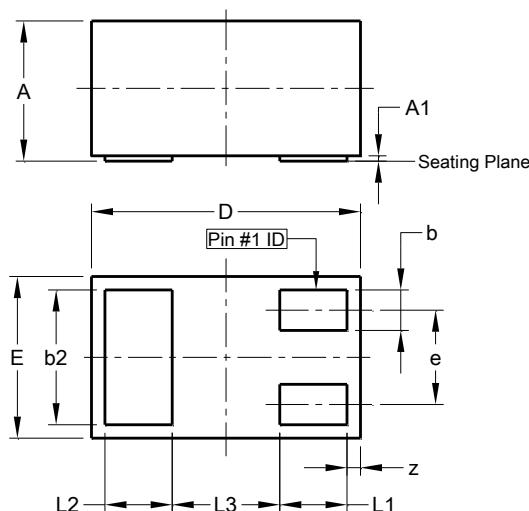


Fig. 7 Typical Base Emitter Saturation Voltage
vs. Collector Current

Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

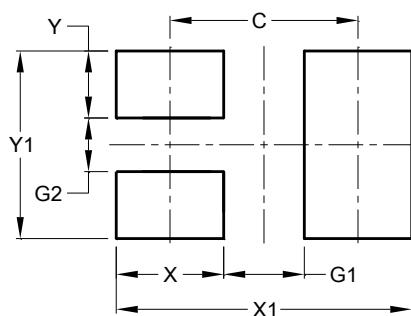


X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05

All Dimensions in mm

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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